

DOCKET NO: 268844US0PCT



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
HIROSHI SHIHO, ET AL. : EXAMINER: CHEN, K. C.
SERIAL NO: 10/529,742 :
FILED: JANUARY 6, 2006 : GROUP ART UNIT: 1765
FOR: POLISHING PAD FOR :
SEMICONDUCTOR WAFER AND
LAMINATED BODY FOR POLISHING OF
SEMICONDUCTOR WAFER EQUIPPED
WITH THE SAME AS WELL AS
METHOD FOR POLISHING OF
SEMICONDUCTOR WAFER

AMENDMENT AND REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the Office Action dated February 9, 2007, Applicants request reconsideration in view of the following amendments and remarks submitted concurrently with a Declaration under 37 C.F.R. §1.132.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Discussion of the Amendment begins on page 9 of this paper.

Remarks begin on page 10 of this paper.

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01 FC:1202
02 FC:1231

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